



TSSOP-48 Lead Free RoHS Profile

| Total Mass of the Unit specified (g): | Product / Component Description | Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.) | Material Name (e.g. Sn alloy) | Substance Name (e.g. Copper (Cu)) | CAS No. | Substance Mass (mg) | PPM | Additional Information |
|---------------------------------------|---------------------------------|--|-------------------------------|-----------------------------------|------------|---------------------|---------|------------------------|
| 0.120 | TSSOP 48L | IC Chip | Silicon doped with aluminium | Silicon (Si) | 7440-21-3 | 6.0225 | 50,178 | |
| | | IC Chip | Silicon doped with aluminium | Aluminium (Al) | 7429-90-5 | 0.012 | 100 | |
| | | IC Lead Frame | Copper alloy | Copper (Cu) | 7440-50-8 | 50.0214 | 416,762 | C7025CDA7025 |
| | | IC Lead Frame | Copper alloy | Nickel (Ni) | 7440-02-0 | 1.5599 | 12,997 | |
| | | IC Lead Frame | Copper alloy | Silicon | 7440-69-9 | 0.3379 | 2,815 | |
| | | IC Lead Frame | Copper alloy | Magnesium | 7439-95-4 | 0.07799 | 650 | |
| | | IC Lead Frame | LF Plating | Silver (Ag) | 7440-22-4 | 0.576 | 4,799 | |
| | | IC Sn solder plating | Tin solder | Tin (Sn) | 7440-31-5 | 3.9472 | 32,887 | 100% Matte Sn plating |
| | | IC die attach | Epoxy filler - Ag | Silver (Ag) | 7440-22-4 | 1.0195 | 8,494 | Ablestik 8290 |
| | | IC die attach | Epoxy base materia | | N/A | 0.3045 | 2,537 | |
| | | IC bond wire | Gold wire | Gold (Au) | 7440-57-5 | 0.3723 | 3,102 | |
| | | IC bond wire | Gold wire | Silver (Ag) | 7440-22-4 | 0.0000019 | 0.02 | |
| | | IC bond wire | Gold wire | Calcium (Ca) | 7440-70-2 | 0.0000082 | 0.07 | |
| | | IC encapsulation | Molding compound | Multi-aromatic (resin) | N/A | 8.9236 | 74,349 | Sumitomo EME G700K |
| | | IC encapsulation | Molding compound | Silica (SiO2) | 60676-86-0 | 46.849 | 390,331 | |

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| Total mass (mg) | 120.02 |
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